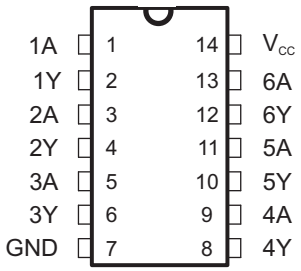
FEATURES

- **Controlled Baseline**
  - **One Assembly Site**
  - **One Test Site**
  - **One Fabrication Site**
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree** (1)
- **Operating Range 2-V to 5.5-V V_{CC}**
- **Unbuffered Outputs**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

(1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

D OR PW PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The 'HC04 devices contain six independent inverters. They perform the Boolean function $Y = \overline{A}$ in positive logic.

ORDERING INFORMATION(1)

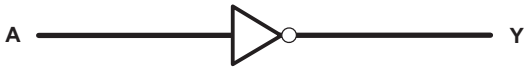
T_A	PACKAGE(2)		ODERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	TSSOP - PW	Tape and Reel	SN74AHCU04MPWREP	AHCU04M

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.
(2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(EACH INVERTER)

INPUT A	OUTPUT Y
H	L
L	H

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	7	V
V_I	Input voltage range(2)		–0.5	7	V
V_O	Output voltage range(2)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0		–20	mA
I_{OK}	Output clamp current	V_O < 0 or V_O = 0 to V_{CC}		±20	mA
I_O	Continuous output current	V_O = 0 to V_{CC}		±25	mA
	Continuous current through V_{CC}or GND	V_{CC} or GND		±50	mA
θ_{JA}	Package thermal impedance(3)	D package		86	°C/W
		PW package		113	
T_{stg}	Storage temperature range		–60	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
(3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.7		V
		V_{CC} = 3 V	2.4		
		V_{CC} = 5.5 V	4.4		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.3	V
		V_{CC} = 3 V		0.6	
		V_{CC} = 5.5 V		1.1	
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-Level output current	V_{CC} = 2 V		–50	µA
		V_{CC} = 3.3 V ± 0.3		–4	mA
		V_{CC} = 5 V ± 0.5		–8	
I_{OL}	Low-Level output current	V_{CC} = 2 V		50	µA
		V_{CC} = 3.3 V ± 0.3		4	mA
		V_{CC} = 5 V ± 0.5		8	
T_A	Operating free-air temperature		–55	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C		T_A = –55°C TO 125°C		UNIT
			MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	2 V	1.8		1.8		V
		3 V	2.7		2.7		
		4.5 V	4		4		
	I_{OH} = –4 mA	3 V	2.58		2.3		
	I_{OH} = –8 mA	4.5 V	3.94		3.5		
V_{OL}	I_{OL} = 50 µA	2 V		0.1		0.2	V
		3 V		0.1		0.3	
		4.5 V		0.1		0.5	
	I_{OL} = 4 mA	3 V		0.26		0.5	
	I_{OL} = 8 mA	4.5 V		0.26		0.5	
I_I	$V_I = V_{CC}$ or GND	0 V to 5.5 V		±0.1		±1	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V		2		20	µA
C_i	$V_I = V_{CC}$ or GND,	5 V		10		10	pF

Switching Characteristics

over operating free-air temperature range, V_{CC} = 3.3 ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C		T_A = –55°C TO 125°C		UNIT
				MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	C_L = 50 pF	1	10.6	1	14	ns
t_{PHL}				1	10.6	1	14	ns

Switching Characteristics

over operating free-air temperature range, V_{CC} = 5 ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C		T_A = –55°C TO 125°C		UNIT
				MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	C_L = 50 pF	1	7	1	11	ns
t_{PHL}				1	7	1	11	ns

Noise Characteristics(1)

V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C

PARAMETER		MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.5		V
$V_{OL(V)}$	Quiet output, minimun dynamic $V_{OL(V)}$		–0.5		V
$V_{OH(V)}$	Quiet output, minimun dynamic V_{OH}		4.3		V
$V_{IH(D)}$	HIgh-level dynamic input voltage $V_{IH(D)}$	4			V
$V_{IL(D)}$	Low-level dynamic input voltage $V_{IH(D)}$			1	V

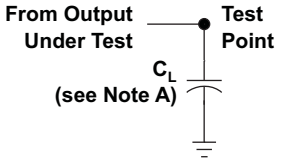
(1) Characterists are for surface-mount packages only.

Operating Characteristics

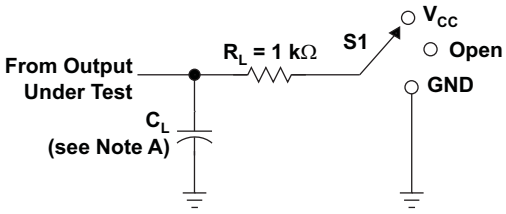
T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load, f = 1 MHz	7.3	pF

PARAMETER MEASURMENT INFORMATION

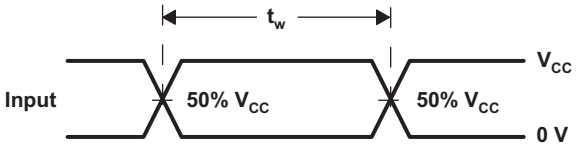


LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

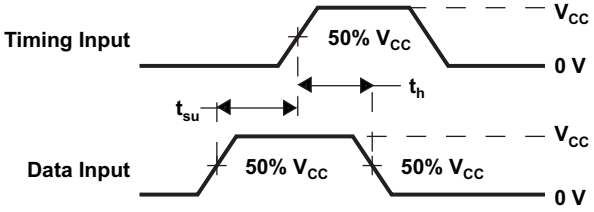


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}

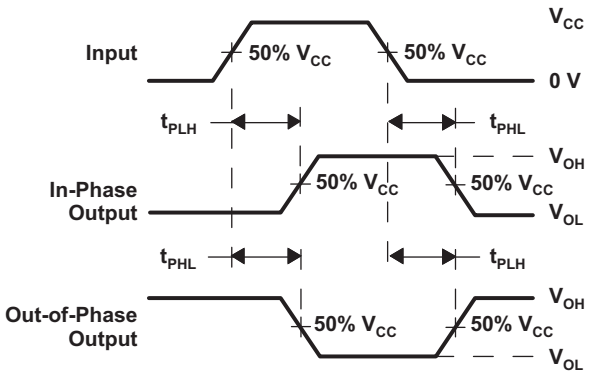
LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS



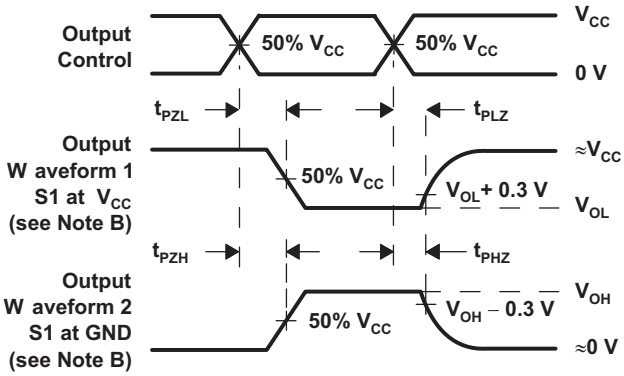
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74AHCU04MPWREP	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCU04M
SN74AHCU04MPWREP.A	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCU04M
V62/07619-01XE	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCU04M

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF SN74AHCU04-EP :

- Catalog : SN74AHCU04

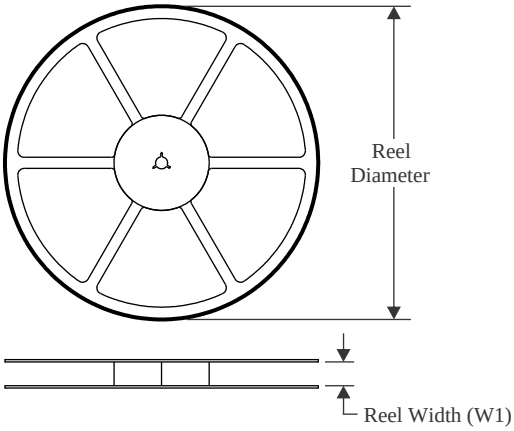
- Automotive : SN74AHCU04-Q1
- Military : SN54AHCU04

NOTE: Qualified Version Definitions:

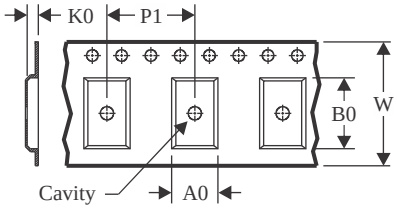
- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

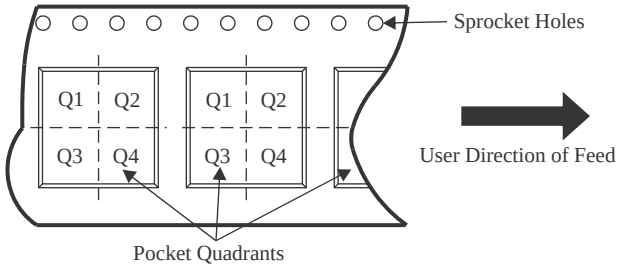


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

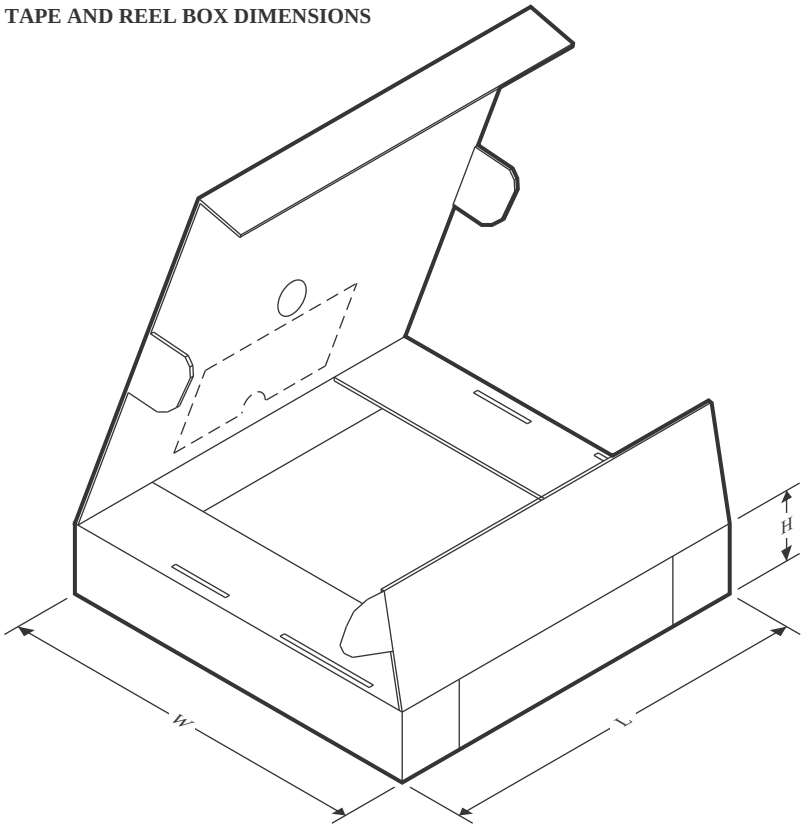
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCU04MPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

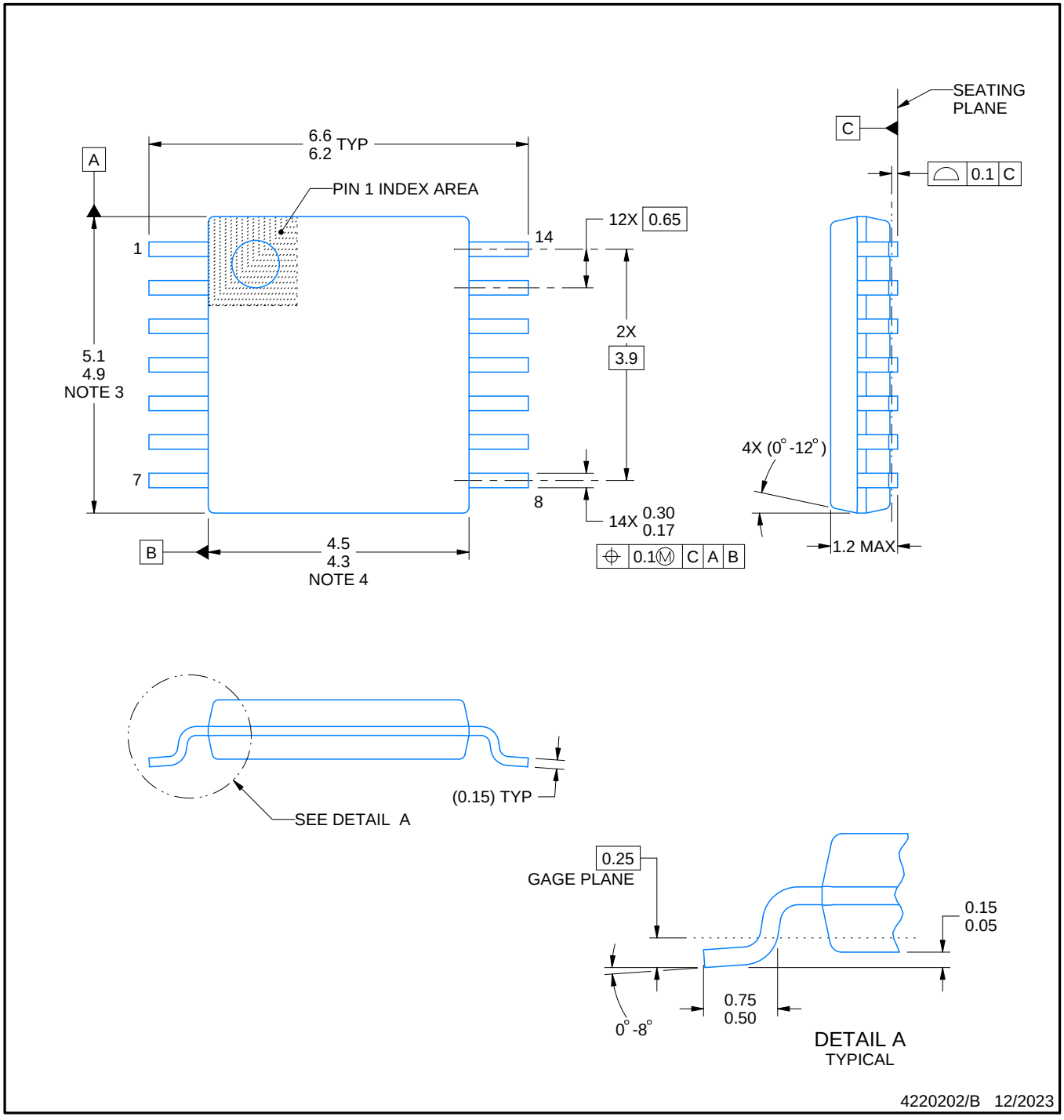
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCU04MPWREP	TSSOP	PW	14	2000	353.0	353.0	32.0

PACKAGE OUTLINE

PW0014A

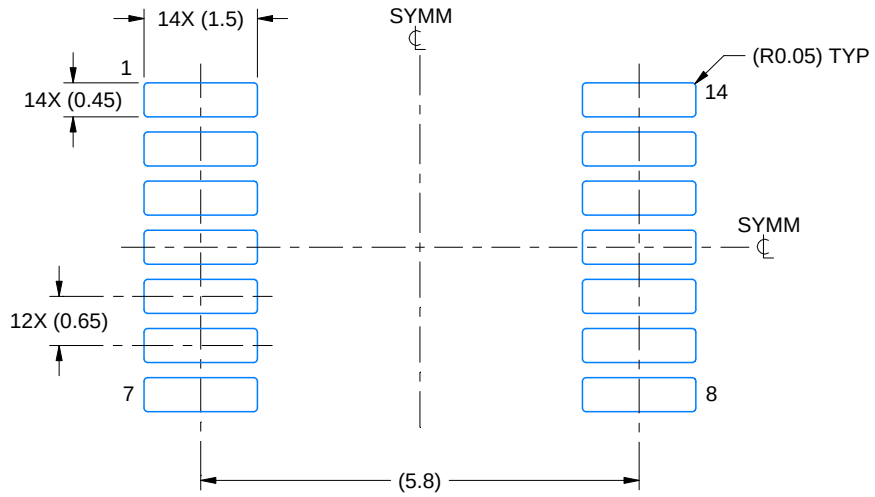
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

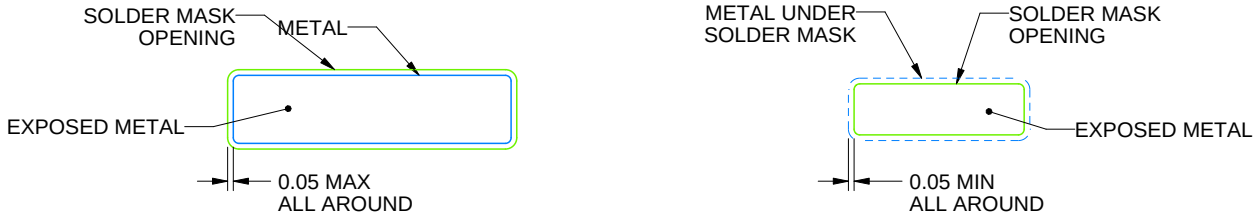


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

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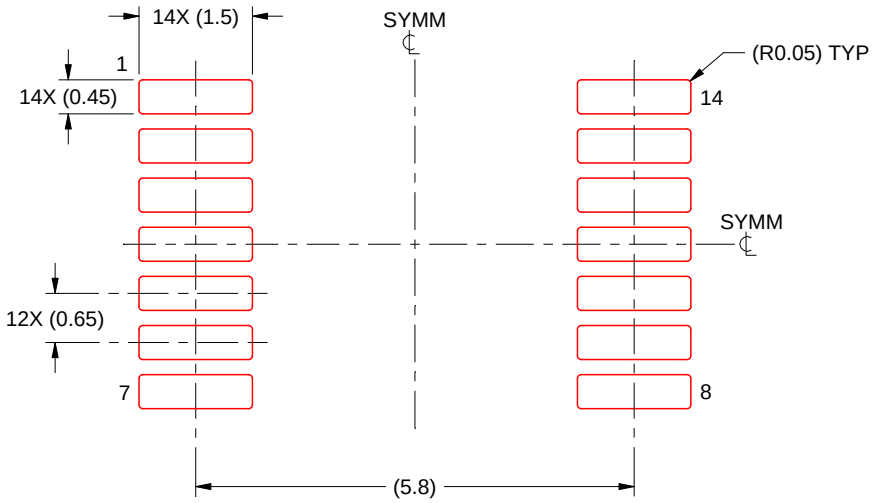
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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